

High-Temperature Hosting Data Center

Testing to Discover the Opportunities and Challenges in High-Temperature
Operating Conditions in a Hosting Data Center



Executive Summary

Today, there is a compelling need for data center efficiency and to find a competitive advantage in the cloud hosting business. Providers need—and are finding ways—to extract greater value from their cloud environments. This document examines high-temperature ambient (HTA) operating conditions and how they affect power consumption of Intel® Xeon® processor E5 family-based servers.

Through a joint project between Intel and a leading European hoster, Intel Xeon processor-based servers were tested and evaluated at key HTA conditions to verify functionality and help the test team understand break-even points between higher inlet air temperatures with resultant power savings versus higher server power consumption and power losses caused by increased fan speeds. The goal was to find the highest potential cooling power savings and also to explore what effects can be encountered with continuously running IT equipment at high temperatures.

Overview

Intel and a leading hosting service provider came together in December of 2012 to understand server operations in an HTA condition to test and evaluate power consumption of Intel Xeon processor-based servers.

Section 2 highlights the testing that was done within a temperature-controlled environment where inlet air temperatures were raised and held at key set points. Various brand-name servers based on Intel Xeon processors were stressed to different utilization levels within these temperature set points. Measurements were taken to understand the resulting changes in power consumption as inlet air temperatures rose from an initial baseline of 18° C up to 38° C. Testing results showed that server power consumption began to increase on all server models at temperatures higher than 28° C. Viewing these results in conjunction with the facilities operating conditions, Intel found that an optimal HTA operating point was

found by staying within an increase of approximately 10° C and maintaining a 28° C environment. This avoided the additional server power consumption observed beyond that temperature level, which offset overall cooling efficiency gains.

To put these results into context, a Romonet Prognose¹ simulated data center model was created to analyze power savings from cooling efficiencies gained in the entire data center as HTA conditions were introduced. Section 3 details the conclusions from this simulation, showing a potential yearly power savings of around 9 percent over the initial baseline of 18° C. These power cost savings are based on cooling efficiency gains around implementing a 28° C HTA environment in an approximately 3,000-square-foot data center, running workloads of 50 percent utilization on all test servers. In the testing, specific power savings yields upwards of €38K per year in energy cost savings based on approximately €420K in total power consumption (Table 1).

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A number of issues with HTA operations need to be weighed. The entire supporting infrastructure must be able to support an HTA environment. The air handling units (AHUs) work more efficiently at higher temperatures, but increasing chilled water temperatures supplied can exceed manufacturers’ specs for expansion in chilled water piping (as the test team encountered, based on current pipe manufacturer specs provided). The team’s recommendations for HTA were considered for future data center environments. Furthermore, high-temperature operation reduces response time for data center personnel and equipment with disaster recovery procedures should a cooling failure occur. A standard 15 minutes of recovery time is reduced to a few minutes due to these reduced safety margins. As a consequence, operational procedures need to be fit to function under these constraints as well.

One way to reduce reaction time in case of such failure was to constantly monitor power data by implementing an Intel® Data Center Manager (Intel® DCM)-based solution. In addition to being able to gather data throughout the data center, this solution also adds power-consumption-limiting capabilities for specific servers², prolonging business continuity time by up to 25 percent in a power outage³. Section 4 provides more background on the enabled usage models in Intel DCM.

Another way to support an HTA environment, with even greater gains, also to be

considered as an element of future data center design, is in the use of free cooling using airside economizers. Directly pulling cold air from outside and venting heated exhaust air through a plenum area for much of the year, coupled with a traditional closed-loop cooling system, provides an even larger reduction in power costs.

When factoring in server throughput, refreshing older-generation systems with new Intel Xeon processor-based servers will typically offer generational improvements of performance-per watt metrics much in line with Moore’s law. Architectural improvements of the server platforms also provide a lower idle power consumption, together improving server usage efficiency (SUE)⁴, a key efficiency metric often not included in power usage effectiveness (PUE) disclosures but greatly useful as part of an overall data center efficiency strategy.

Section 5 summarizes and recommends these and other measures.

Empirical Data Center Tests

Testing Methodology

The methodology consisted of testing Intel® architecture-based servers in an HTA with dedicated workloads while focusing on the effects of the temperature on server power consumption. Servers using Intel architecture provide real-time temperature sensor and power consumption data, which was used during the testing. Along with the server data, a temperature-controlled

Table 1. Server Types

Server Type	Amount
IBM System x3550*, System x3550 M4*, System x3250 M2*, System x306M* Intel® Server System R2216GZ4GCLX	13x
Storage: 14x 100 GB SSD (Intel® Solid-State Drive Series 710) Intel Server System H2216WPQJR	1x
Storage: 14x 600 GB SSDs (Intel Solid-State Drive Series 310) 2x 240 GB SSDs (Intel Solid-State Drive Series 540)	4x
HP DL360p Gen8 (Intel® Xeon® processor E5 family)	2x

server aisle environment was utilized, where servers were stressed to specific multiple utilization levels using synthetic workloads. While stressing the systems, heating units maintained inlet temperatures within the contained cold aisle of 24° C, 28° C, 33° C, and 38° C, respectively. Testing server power consumption incorporated using data drawn from smart PDUs and Intel DCM software to monitor power supply power consumption, and wall power being reported by the servers.

The following components were part of the experimental setup:

- Separate contained server room with controllable ambient temperature using remote temperature-controlled units
- Multi-generational sample of HP ProLiant*, IBM xSeries*, and Intel Xeon processor-based server systems
- Measurements of power draw at a range of temperatures and server utilizations
- Temperature range: 24° C, 28° C, 33° C, and 38° C

- Server load testing of 25, 50, 75, and 100 percent utilization
- Temperature sensors on server racks at 22U and 42U height were utilized for validating inlet and outlet sensor readings in the servers.

Lab Setup

The server pool consisted of samples of machines used in the hosting provider’s production and thus represented in a smaller-scale the distribution of a historically grown data center.

All servers were equipped with the Windows* 2008 R2 operating system. Testing software was Passmark Software’s Burn-In-Test* v5.3. All servers were connected to a central management station.

Experimental Results

Figures 1 and 2 show power consumption with two-server system types of different generations. These graphs highlight power consumed in amperes (A) at 230 VAC across inlet temperatures ranging from 24 to 38° C and utilizations ranging from 25 to 100 percent.

The current Intel Xeon processor E5-2620 product family-based server exhibited the lowest power consumption, with around 33° C inlet temperature and a noticeable power increase above that, especially during high utilization, as shown in Figure 1. The likely cause of this effect is the combined power consumption of the server’s fans as they respond to the increased inlet temperatures and the maximum power consumption of the processor itself.

In contrast to Figure 1, an earlier-generation server is characterized in Figure 2 (one of the IBM x3350 machines dating from approximately 2008). Two areas of difference are clearly visible:

1. Power consumption at low utilization is much higher than with newer, more efficient server designs.
2. The relative increase in power consumption with raised temperatures and utilizations is therefore much smaller, since the server started out with a higher initial idle power consumption.

Overall, the power consumption difference over the combined range of temperatures

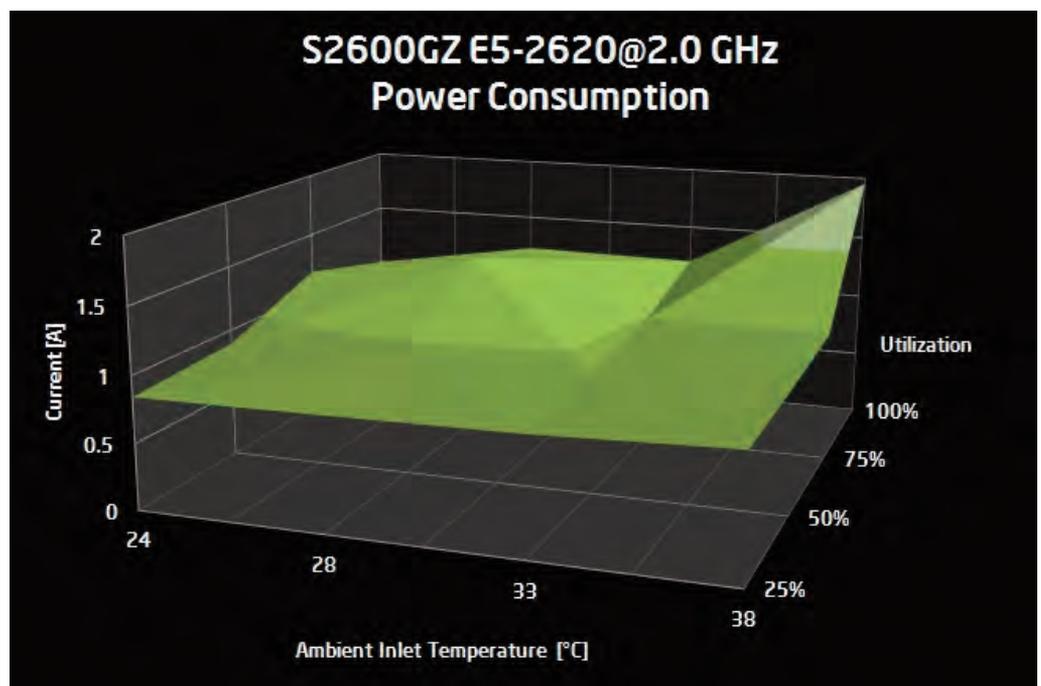


Figure 1. Power consumption of Intel Xeon processor E5 family equipped server as a function of inlet temperature and CPU utilization

and utilizations remains smaller. Thus, the effect of changing temperatures has less obvious advantages. Still, a noticeable local optimum for this type of machine can be found at around 28° C as well.

Calculating Savings

Providing a blueprint for data center efficiency is helpful in understanding future required changes and potential savings based on those changes. A simulation using Romonet Prognose* 2.1 software was used to this end. Site power consumption and operational equipment costs were provided by hosting partner to calibrate the Romonet model, while data from the server experiments was the source of simulated IT equipment power.

Romonet Model

Based on initial data center power costs and savings seen during actual testing, data was included in simulated models created to run potential HTA scenarios and model future data center power savings. The results were that HTA has the potential to yield upwards of 50 KWh in power savings and €38K per year in power cost savings. Because actual testing showed a 10 percent increase in server power consumption (from 28° C to 33° C

HTA), savings decreased as temperatures continued to increase. The expected power saving benefits of €44K per year are offset with IT power increases of equipment (Table 2).

HTA Model Assumptions

In the model, it was assumed that the cooling infrastructure could support HTA and higher chilled-water temperatures (CWT). PUE numbers are based on the Romonet model and demonstrate a PUE trend downward based on future data center HTA design changes made. All models are assuming a 50 percent load on IT equipment. Additional numbers were added for items such as office lighting, generator pre-heat power loads, and splits between two UPSs at 75 and 25 percent.

Efficiency Model Variations

Discrete steps were simulated as a step-wise strategy of data center improvements. Starting from an as-is model with an inlet air temperature of 16° C, the model was changed in the following fashion:

- **Step 1:** Raised chilled water temperature to 18° C (resulting in inlet air temperature of 24° C).

- **Step 2:** Changed simulated CRAC control algorithm to be based on wet bulb temperature measurements (when temp is low, you get a few more operating degrees) but at the same nominal temperature.
- **Step 3:** Increased chilled water temp to 22° C (inlet air 28° C).
- **Step 4:** Chilled water temp to 27° C (inlet air 33° C).

Ultimately, moving from 16° C supply air to 28° C supply air temperature decreases cooling power usage by €37,620 (Table 2).

Efficiency Gains

From Figure 3, we see that at an 11° C outside temperature, the model switches over from the cooling tower to the chiller. Once the chiller has to be utilized for cooling, there is a reduction in the data center infrastructure efficiency (DCIE). This big jump in the power consumption reduces efficiency. As such, by running in an HTA environment, the chiller is utilized much less and only at much higher temperatures, allowing for the majority of savings seen in the model.

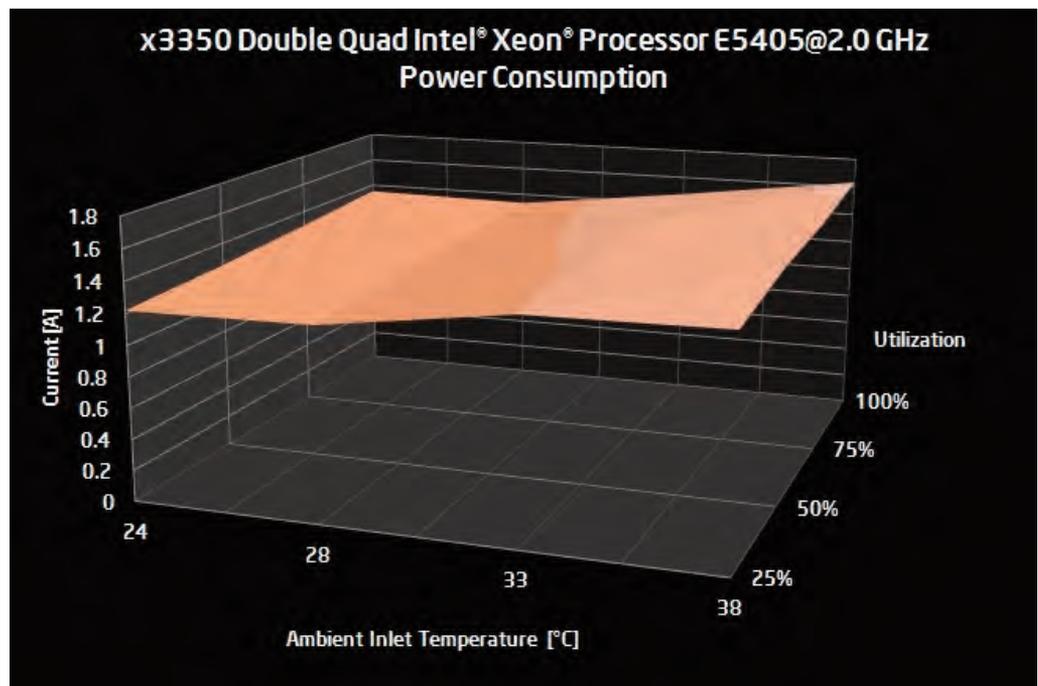


Figure 2. Power consumption of earlier-generation server as a function of inlet temperature and CPU utilization

Proactive Management

Instrumentation of server infrastructure is a key feature in monitoring and managing IT power consumption for data center efficiency and resiliency.

Power Capping

Intel® Node Manager (Intel® NM) is in-server instrumentation for the measurement and control of key environmental parameters (e.g., power consumption, fan speed, and temperatures). Intel NM allows collecting measurements and reporting them to a

management station via out-of-band communication through IPMI. Intel NM also implements a power-limiting feature called power capping.

Intel DCM is a software development kit (SDK) with a graphical user interface that allows the collection of measurements from a potentially large group of instrumented servers, storing them in a database for later analysis, and—if supported by technologies such as Intel NM—offers capabilities to apply flexible power capping policies to larger pools of servers.

Use Cases

These two tools are valuable aids in managing data center power consumption. Combined, they enable the following use cases and their associated business benefits:

1. **Rack provisioning and capacity planning**
 - Actual power measurements improve accuracy for rack power maximums and minimums.trends.

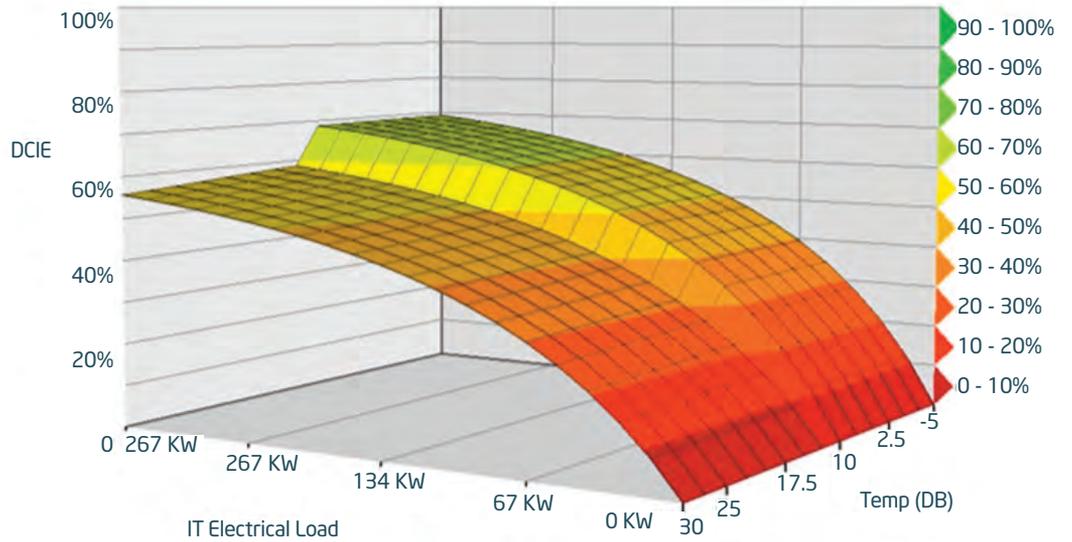


Figure 3. Center infrastructure efficiency (DCIE) chart for simulated data center

Table 2. Romonet Model Parameters Simulating Stepwise Data Center Improvements

Cost Summary				CRAC Settings								
PUE	GWh	Energy Cost/Year (€)	CWT Set-point	Tower/Chiller Cu-tower	Max. Condenser Air Temp.	CRAC CWT	Supply-Side Temp.	Return-Side Air Temp.	System Inlet Temp.	Power Inc. Parameter	Extra IT Load	
As-Is	1.623	3.805	418.5K	10	11	38	10	16	28	16	1	0%
Step 1	1.565	3.671	403.8K	18	13	46	18	23	36	24	9	0%
Step 2	1.515	3.553	390.8K	18	13	46	18	23	36	24	9	0%
Step 3	1.476	3.463	380.9K	22	17	50	22	27	40	28	Wet Bulb: 13 - 17 C	0.6%
Step 4	1.452	3.405	374.5K	27	22	55	27	32	45	33	Wet Bulb: 13 - 23 C	10%

- Monitored power can be used to understand daily or weekly power usage trends.
- Measured power can be used to understand maximums to determine and improve rack server density.
- Enable the ability to install additional servers per rack based on power capping policies ability to enforce a global cap.
- The payoff: Potential increase in rack density by 40 percent⁵.

2. Intelligent power strip replacement

- Avoids the cost of expensive power strips using built-in power monitoring capacity.

3. Disaster avoidance under impaired conditions

- Protects hours of work lost if unscheduled shutdown happens.
- Enables real-time assessment of power margins and power budgeting for continued operation.
- Enables prioritizing of power allocation to servers in case of an outage using dynamic policies.

4. Server infrastructure scheduling to meet workload demand (Figure 4)

5. Building real-time thermal maps of data center to manage heat loads and distribute dynamically in a virtualized cloud computing environment (Figure 5).

6. Identifying high power idle and underutilized servers

- Provides the ability to monitor and resolve high idle servers and those that are underutilized.
- Provides the ability to efficiently use server infrastructure based on fixing or refreshing older servers.

Power Capping Assumption

Experience shows, across a range of workloads, that applying a 5 percent power cap (setting an external limit of power consumption to 95 percent of the measured maximum) will usually not affect service level agreements (SLAs) and should be considered as an additional tool to reduce chiller operation in warmer months (Source: Intel IT).

Conclusions and Recommendations

Energy costs continue to drive innovation, so finding every area where efficiencies can be increased is essential. In fact, efficient use of power may be the single biggest factor in determining server total cost of ownership (TCO). The above outlined areas observed by Intel provide pieces to the power efficiency puzzle. An overall power efficiency strategy is required for managing a reduction of power consumption. This consists of HTA design practices, air containment, airside economizers for cooling efficiency, power-efficient servers for improved power management, and software tools that provide power analytics and dynamic management to optimize the compute environment.

Performance and Power Testing

Performing actual HTA testing helped Intel understand how these conditions affected power consumption of Intel

Xeon processor-based servers. These servers were stressed to different utilization levels and different inlet air temperatures. Data was captured using smart PDUs, Intel DCM, and temperature rack-mounted sensors. The initial baseline inlet server air temperatures of approximately 16° C/18° C and were raised to set points of 24° C, 28° C, 33° C, and 38° C running server loads of 25, 50, 75, and 100 percent utilization.

Based on testing results, Intel found there was an optimal set point for HTA operations by staying within an increase of 10° C up to a temperature of 28° C, where server power consumption stayed relatively constant. Testing showed no substantial measured increases in server power consumption (at 28° C there was a 1 percent increase in server power) within this range, so the efficiency gains in cooling infrastructure were maximized up to that point by not being offset by server power increases. (On the other hand, at 33° C there was a 12 percent increase in server power.) Additionally, server function was not affected by HTA conditions of up to 38° C.

Key Findings

- The optimum set point after increasing temperatures was 28° C. The increased IT power consumption of tested servers at this temperature was less than a 1 percent increase.
- Simulated power consumption savings from increasing temperatures resulted in annual power savings of at least 9 percent of total power. These results took into account the geographic location of the hosting data center and average weather

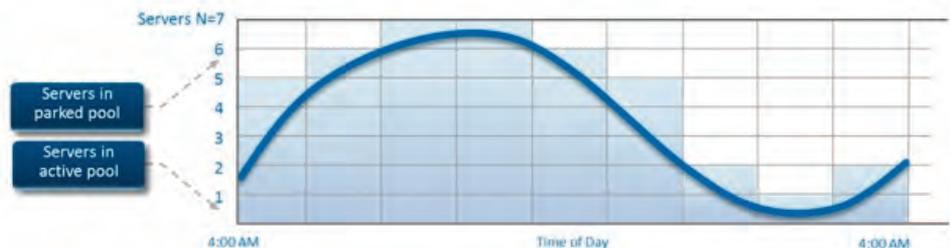


Figure 4. Servers in a pool are dynamically activated or deactivated whenever workload thresholds are crossed

conditions along with other assumptions (see High Temperature Ambient [HTA] Model Assumptions).

- High-temperature operations in future data center designs should be coupled with airside economizer usage to maximize free cooling benefits when outside temperatures are below the desired set point of 28° C.
- Power management technologies such as Intel DCM, coupled with Intel NM, will manage and reduce power consumption by dynamically controlling server power usage.
- Refreshing with new, power-managed servers provides lower idle power consumption and higher performance per watt of power efficiency.

Outlook and Next Steps

Along with HTA, key data center design best practices and technologies should be looked at for overall efficiency gains and in aiding in developing an overall data center efficiency strategy.

Containment and Raised Floors

Best practices for data center design include containment of hot or cold aisles. This suggestion, based on Intel IT best practices, includes employing hot aisle containment with the use of a plenum (false ceiling) and ducting to the plenum from CRAC units. This allows the addition of airside economizers to be included in these future designs and the venting of heated exhaust air directly outside. Another key recommendation is to eliminate a raised floor, thus saving money in construction costs. An airside economizer (AHU) can pressurize the entire room instead of just the under-floor area.

Airside Economizers

Airside economizers can be included in future data center module designs for cooling efficiency, based on a temperate climate for much of the calendar year. Also, specifically for Internet hosters, the ability to have different Tier⁶ ratings in different data centers allows for power savings for lower tier customers (Tier 1/2) and a competitive advantage for cost sav-

ings, since designs don't have to be created to the highest-tier customer. These designs and potential additional savings with airside economizers and reduced redundancy in UPS, cooling, and removal of raised floor is worth investigating.

Server Refresh

Key findings of older servers (four-plus years old) show that you can achieve a 10:1 consolidation ratio on average by replacing older servers based on single-core technology⁷. The power consumption is reduced not only by requiring fewer servers, but additional efficiencies are realized when at low utilization or idle states.

From the testing completed, it was noted that older servers were consuming power at much higher rates than newer, more efficient servers. This is significant in a hosting business model. In a dedicated or physical hosting scenario, each customer is assigned their own physical server and, therefore, ultimately responsible for the server's utilization. Consequently, these machines tend to exhibit rather low levels of compute usage. This inefficiency is magnified when high

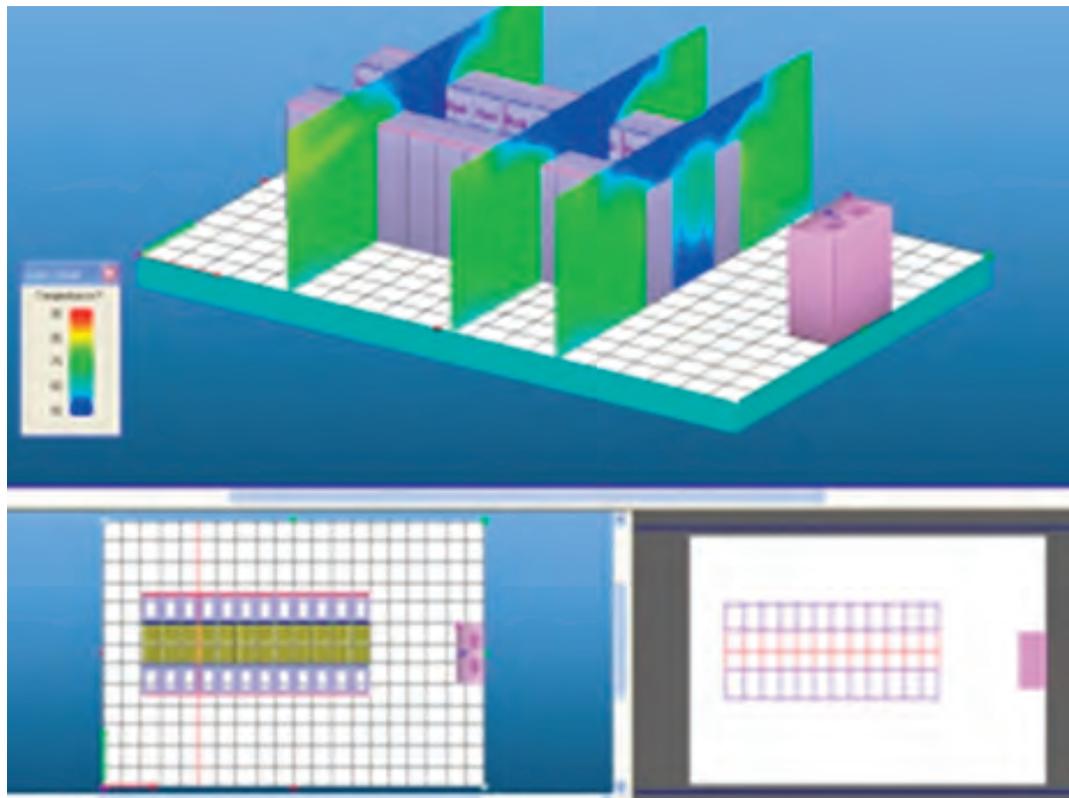


Figure 5. Data center infrastructure management software is using monitored temperature values to visualize a real-time heat map of a data center.

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idle power consumption rates of older servers are used. Refreshing these servers with new models reduces IT power consumption costs.

In the context of a virtualized hosting data center, customers are assigned virtual machines that can be freely placed and consolidated by the hosting provider on the lowest possible number of servers. Higher

consolidation ratios of newer servers also reduce costs and this consolidation effect provides opportunities to right-size IT equipment for this business model.

DCIM Tools

Intel DCM is part of many commercial data center infrastructure management (DCIM) solutions. It supports advanced usage mod-

els ranging from comprehensive real-time monitoring through rack density optimizations and advanced resiliency mechanisms to power and thermal-aware workload scheduling mechanisms.

Find a complete list of solution vendors here.

¹ See <http://www.romonet.com/romonet-software> for a description of this tool.

² Intel DCM, Supported devices (<http://software.intel.com/sites/datacentermanager/supported-devices.php>).

³ Data Center Energy Efficiency Using Intel® Intelligent Power Node Manager and Intel® Data Center Manager” (http://software.intel.com/sites/datacentermanager/White%20Paper_CHT_and_Intel_Power_Management_Technologies_v1.pdf).

⁴ “Assessing IT Efficiency through Server Utilization Effectiveness,” William Carter, Data Center World, Spring 2012 conference proceedings.

⁵ Baidu Case Study White Paper, “Intelligent Power Optimization for Higher Server Density Racks” (http://software.intel.com/sites/datacentermanager/intel_node_manager_v2e.pdf).

⁶ See Tier ratings based on The Uptime Institute (<http://uptimeinstitute.com/>).

⁷ “Staying committed to Server Refresh Reduces Cost” (<http://www.intel.com/content/www/us/en/windows-7-upgrade/intel-it-pc-refresh-staying-committed-to-server-refresh-reduces-cost-brief.html?wapkw=server+refresh>).

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